

### General Description

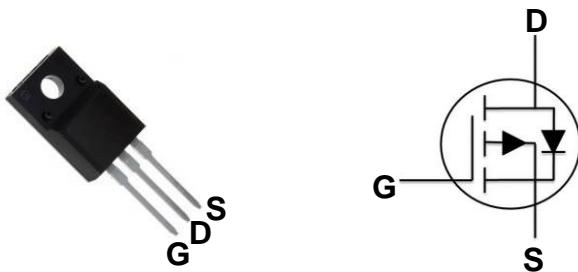
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDS(ON)	ID
-100V	140mΩ	-10A

### Features

- -100V,-10A, RDS(ON) 140mΩ@VGS = -10V
- VGS Guarantee  $\pm 25V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

### TO220F Pin Configuration



### Applications

- Networking
- Load Switch
- LED applications



### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-100	V
$V_{GS}$	Gate-Source Voltage	$\pm 25$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	-10	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	-6.5	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	-40	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	48	W
	Power Dissipation – Derate above 25°C	0.38	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.6	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-100	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$	---	---	---	$\text{V}^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-100\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{\text{DS}}=-80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	-10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 25\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-6\text{A}$	---	115	140	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-3\text{A}$	---	130	170	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1	---	-3	V
			---	---	---	$\text{mV}^\circ\text{C}$

**Dynamic and switching Characteristics**

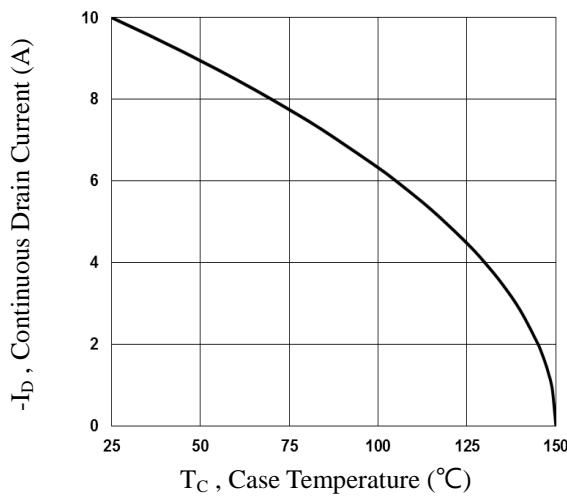
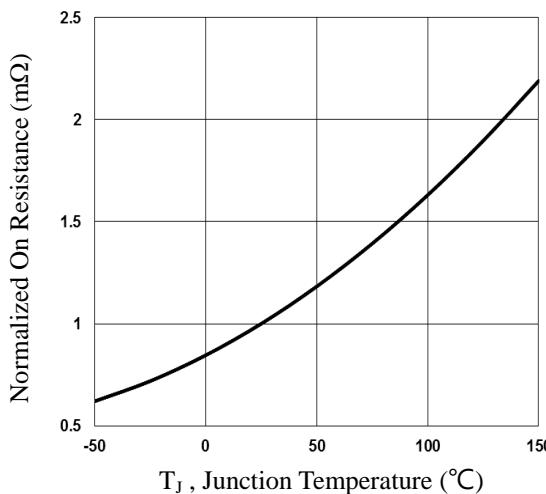
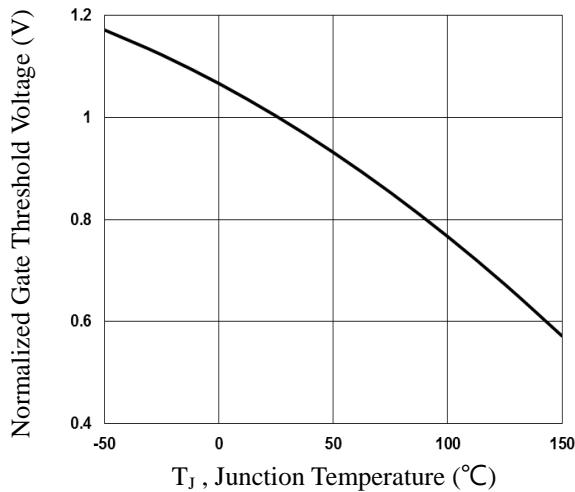
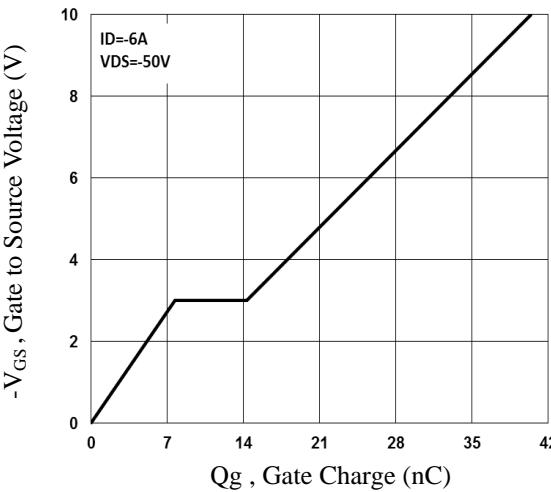
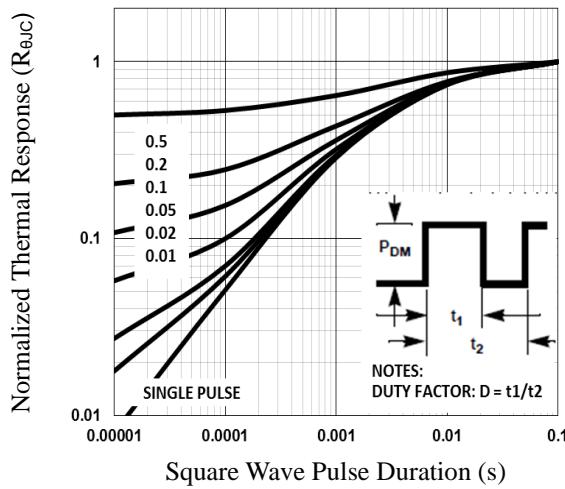
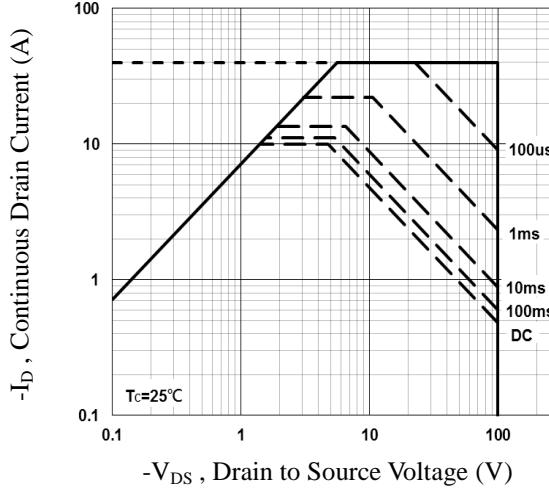
$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{\text{DS}}=-50\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-6\text{A}$	---	40.4	70	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2,3</sup>		---	7.7	15	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2,3</sup>		---	6.6	13	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2,3</sup>	$V_{\text{DD}}=-30\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_{\text{G}}=6\Omega$ $I_{\text{D}}=-1\text{A}$	---	27	54	ns
$T_r$	Rise Time <sup>2,3</sup>		---	12	24	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2,3</sup>		---	150	300	
$T_f$	Fall Time <sup>2,3</sup>		---	45	90	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	2250	3900	pF
$C_{\text{oss}}$	Output Capacitance		---	130	250	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	90	180	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	10	---	$\Omega$

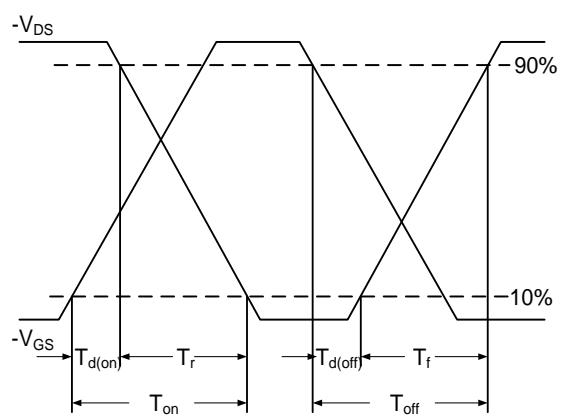
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-22	A
			---	---	-88	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.1	V
			---	---	---	ns
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	---	---	---	ns
			---	---	---	$\mu\text{C}$

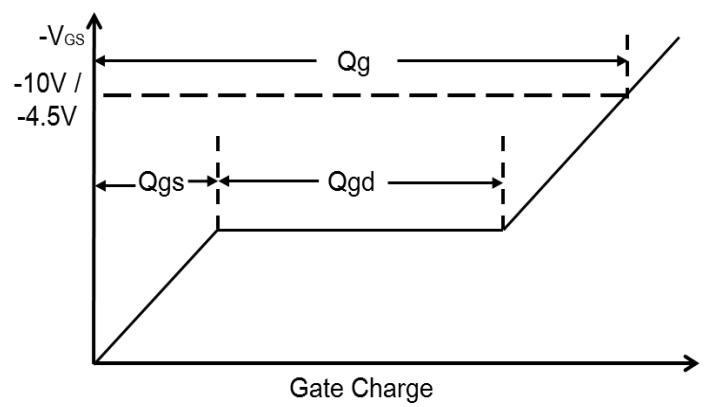
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

**Fig.1 Continuous Drain Current vs.  $T_C$** **Fig.2 Normalized RD<sub>SON</sub> vs.  $T_J$** **Fig.3 Normalized  $V_{th}$  vs.  $T_J$** **Fig.4 Gate Charge Waveform****Fig.5 Normalized Transient Impedance****Fig.6 Maximum Safe Operation Area**



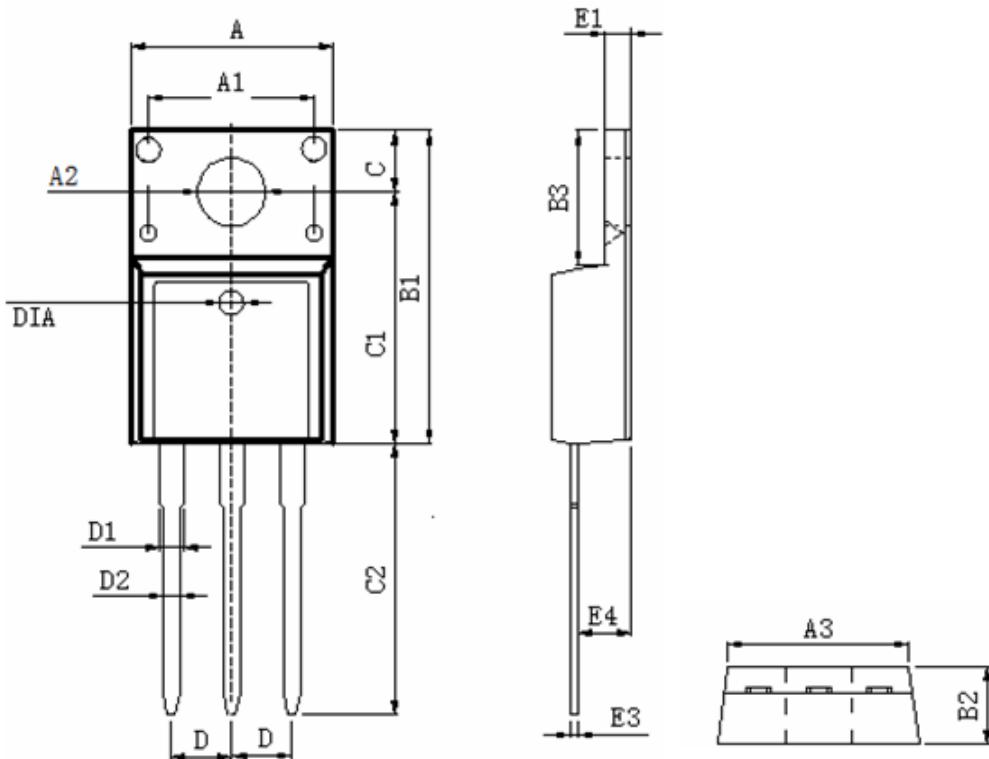
**Fig.7** Switching Time Waveform



**Fig.8** Gate Charge Waveform



## TO220F PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.460	9.860	0.412	0.388
A1	7.100	6.900	0.280	0.272
A2	3.500	3.100	0.138	0.122
A3	9.900	9.500	0.390	0.374
B1	16.170	15.570	0.637	0.613
B2	4.900	4.500	0.193	0.177
B3	6.880	6.480	0.271	0.255
C	3.500	3.100	0.138	0.122
C1	12.870	12.270	0.507	0.483
C2	13.380	12.580	0.527	0.495
D	2.590	2.490	0.102	0.098
D1	1.470	1.070	0.058	0.042
D2	0.900	0.700	0.035	0.028
E1	2.740	2.340	0.108	0.092
E3	0.600	0.400	0.024	0.016
E4	2.960	2.560	0.117	0.101
DIA	Φ1.5 TYP.	deep0.1 TYP.	Φ0.059 TYP.	deep0.004 TYP.